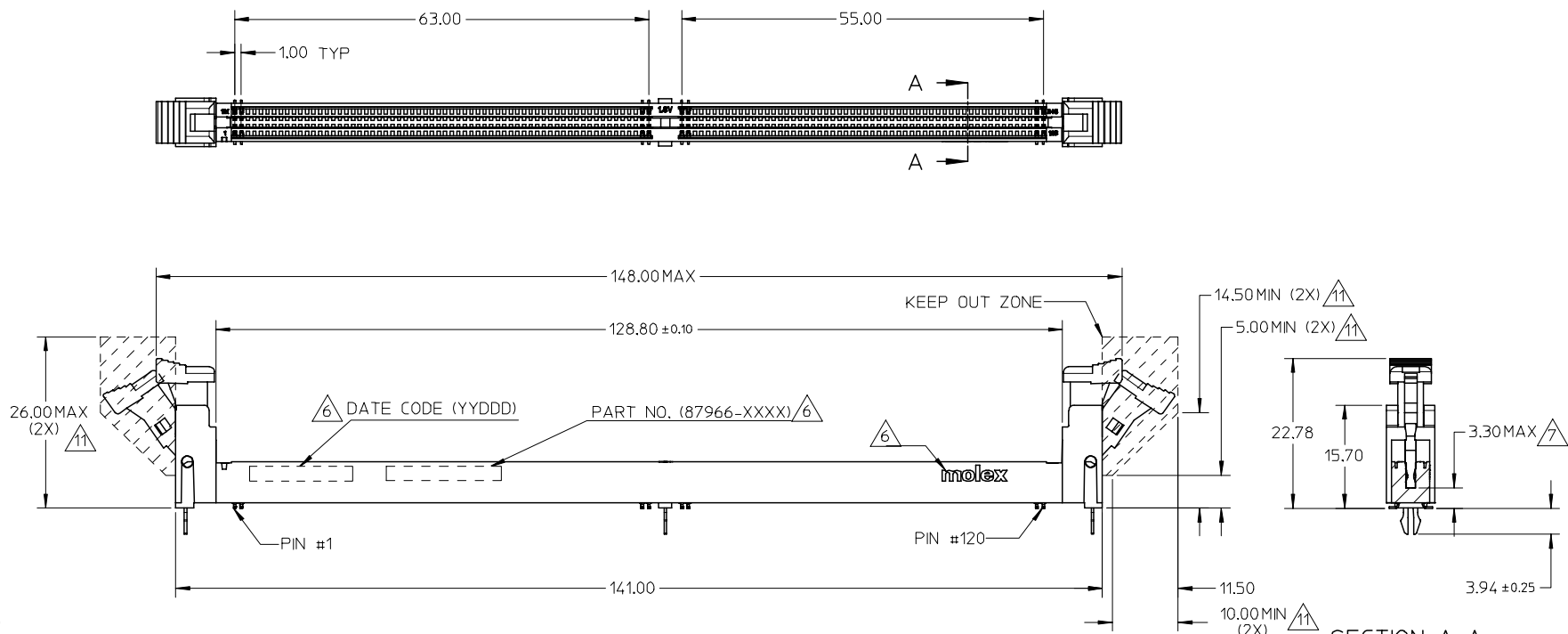




NOTES:

1. MATERIALS

HOUSING - HIGH TEMP LCP GLASS FILLED, UL 94V-0, BLACK
 EJECTORS - HIGH TEMP NYLON GLASS FILLED, UL 94V-0, BLACK
 TERMINALS - COPPER ALLOY

2. PLATING OPTION - PLS REFER TO SHEET 5.

3. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS. (MEASURED OVER PC PADS)

4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237. PLS REFER TO SHEET 3.

5. PRODUCT IS PACKED INTO TRAYS.

6. MOLEX LOGO, DATE CODE & PART NO. INDICATED ON HOUSING.

7. DIMM MODULE SEATING PLANE FROM TOP OF PCB.

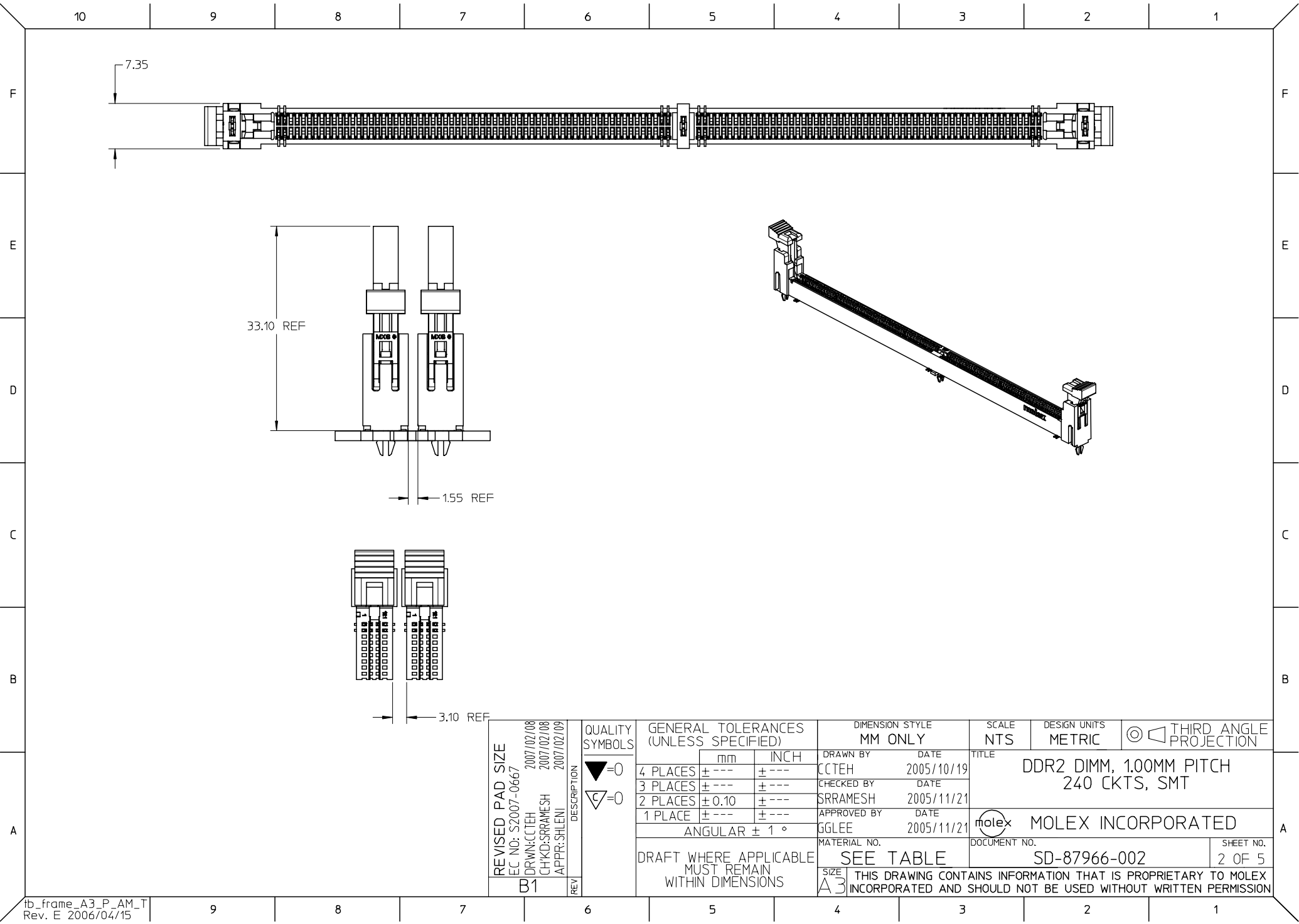
8. COPLANARITY FOR SOLDER TAILS SHALL NOT EXCEED 0.20MM. 9. REFER TO PRODUCT SPEC. PS-87966-001 FOR PERFORMANCE SPECIFICATIONS.

10. THE KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB, WHICH DOES NOT INCLUDE THE LATCH.

11. KEEP OUT ZONE AS PER JEDEC SO-001.

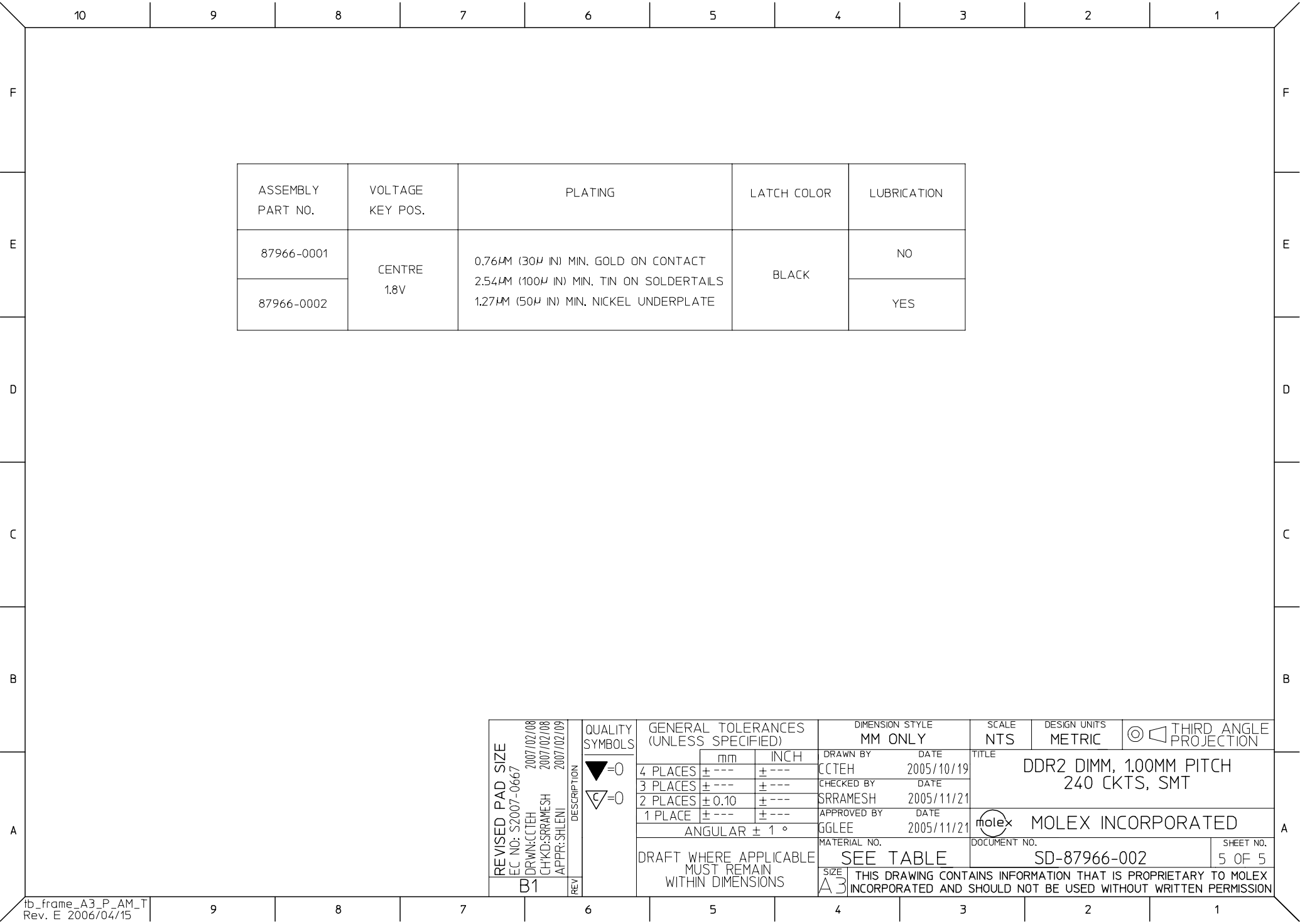
12. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

REVISED PAD SIZE EC NO: S2007-0667 DRAWN:CCTEH CHKD:SRAMESH APPR:SHLENI		2007/02/08 2007/02/08 2007/02/09		DESCRIPTION		QUALITY SYMBOLS		GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE				SCALE		DESIGN UNITS		 THIRD ANGLE PROJECTION	
						NTS		METRIC		MM ONLY		DRAWN BY		DATE		TITLE					
B1		REV				 =0  =0		mm		INCH		CCTEH		2005/10/19		DDR2 DIMM, 1.00MM PITCH 240 CKTS, SMT					
								4 PLACES ± --- ± ---		CHECKED BY		DATE									
								3 PLACES ± --- ± ---		SRRAMESH		2005/11/21		MOLEX INCORPORATED							
								2 PLACES ± 0.10 ± ---		APPROVED BY		DATE									
								1 PLACE ± --- ± ---		GGLLEE		2005/11/21									
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						ANGULAR ± 1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.									
						SEE TABLE		SD-87966-002		1 OF 5											
						SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													





tb_frame_A3_P_AM_T
Rev. E 2006/04/15



ASSEMBLY PART NO.	VOLTAGE KEY POS.	PLATING	LATCH COLOR	LUBRICATION
87966-0001	CENTRE 1.8V	0.76µM (30µ IN) MIN. GOLD ON CONTACT 2.54µM (100µ IN) MIN. TIN ON SOLDERTAILS 1.27µM (50µ IN) MIN. NICKEL UNDERPLATE	BLACK	NO
87966-0002				YES

REVISED PAD SIZE EC NO: S2007-0667 DRWN:CTEH 2007/02/08 CHKD:SRAMESH 2007/02/08 APPR:SHLENI 2007/02/09 B1	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		▽=0 ▽C=0		mm	INCH	DRAWN BY	DATE	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, SMT	MOLEX MOLEX INCORPORATED	SHEET NO. 5 OF 5
			4 PLACES	± ---	± ---	CTEH	2005/10/19			
			3 PLACES	± ---	± ---	CHECKED BY	DATE			
			2 PLACES	± 0.10	± ---	SRAMESH	2005/11/21			
			1 PLACE	± ---	± ---	APPROVED BY	DATE			
		ANGULAR ± 1 °			GGLEE		2005/11/21			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87966-002		
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				